

RELIABILITY REPORT
FOR
MAX4069AUB
PLASTIC ENCAPSULATED DEVICES

June 3, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

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Conclusion

The MAX4069 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I.Device Description	V.Quality Assurance Information
II.Manufacturing Information	VI.Reliability Evaluation
III.Packaging Information	IV.Die Information
Attachments

I. Device Description

A. General

The MAX4069 low-cost, bidirectional, high-side, current-sense amplifier is ideal for monitoring battery charge and discharge currents in notebooks, cell phones, and other portable equipment. It features up to 24V input common-mode voltage range, low 100 μ A supply current (which drops to only 10 μ A in shutdown), and a total output error of less than 1.5%. The wide 1.35V to 24V input common-mode range is independent of the supply voltage, ensuring that the current-sense feedback remains accurate even when connected to a battery pack in deep discharge.

To achieve maximum flexibility, an external current-sense resistor is used along with a Gain Select pin to choose either 50V/V or 100V/V. A single output pin continuously monitors the transition from charge to discharge and avoids the need for a separate polarity output. The MAX4069 has an adjustable reference voltage, set by two external resistors.

The MAX4069 operates from a 2.7V to 24V single supply. The device is specified over the automotive operating temperature range, -40°C to +125°C. The MAX4069 is available in a 10-pin μ MAX package.

B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
VCC, RS+, RS- to GND	-0.3V to +26V
OUT to GND	-0.3V to Lesser of (VCC + 0.3V) or 15V
Differential Input Voltage (VRS+ - VRS-)	± 0.3 V
GSEL, SHDN, REFOUT, REFIN and ADJ to GND	-0.3V to (VCC + 0.3V)
OUT Short-Circuit Duration to GND or to Lesser of (VCC or 15V)	Continuous
REFOUT Short Circuit to VCC or GND	Continuous
Current into Any Pin	± 20 mA
Operating Temperature Range	-40°C to +125°C
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
10-Pin μ MAX	444mW
Derates above +70°C	
10-Pin μ MAX	5.6mW/°C

II. Manufacturing Information

A. Description/Function:	Bidirectional, High-Side, Current-Sense Amplifiers with Reference
B. Process:	S12 (Standard 1.2 micron silicon gate CMOS)
C. Number of Device Transistors:	338
D. Fabrication Location:	Oregon or California, USA
E. Assembly Location:	Philippines, Thailand or Malaysia
F. Date of Initial Production:	March, 2002

III. Packaging Information

A. Package Type:	10-Pin μMAX
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-2501-0205
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112:	Level 1

IV. Die Information

A. Dimensions:	59 x 67 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Manager, Rel Operations)
Bryan Preeshl (Executive Director)
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 44 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

↑
Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 24.68 \times 10^{-9}$$

$$\lambda = 24.68 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-5917) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The OX97 die type has been found to have all pins able to withstand a transient pulse of $\pm 1000\text{V}$, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 50\text{mA}$.

Table 1
Reliability Evaluation Test Results

MAX4069AUB

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		44	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	μMAX	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

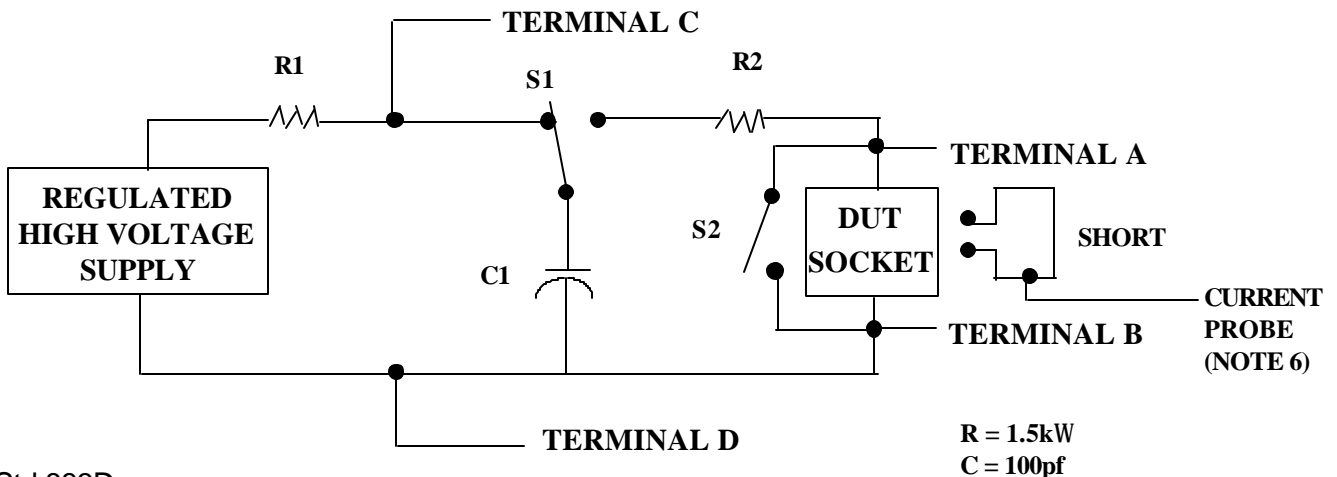
2/ No connects are not to be tested.

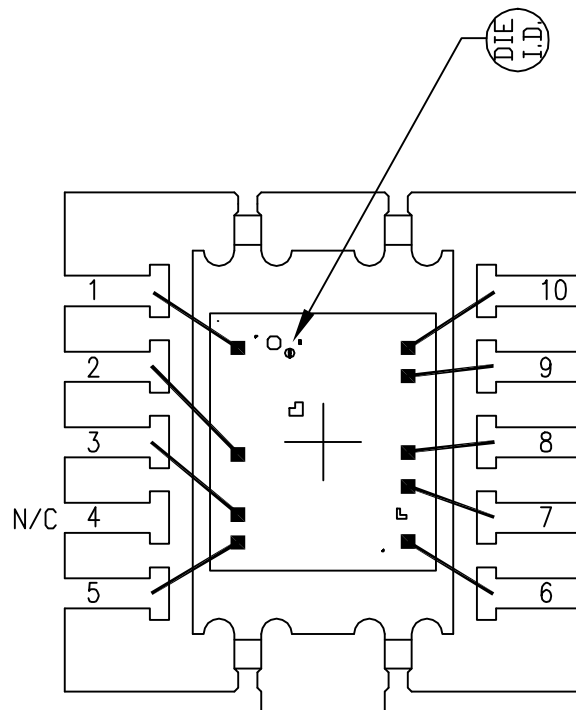
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, $+V_S$, $-V_S$, V_{REF} , etc).

3.4 Pin combinations to be tested.

- Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.

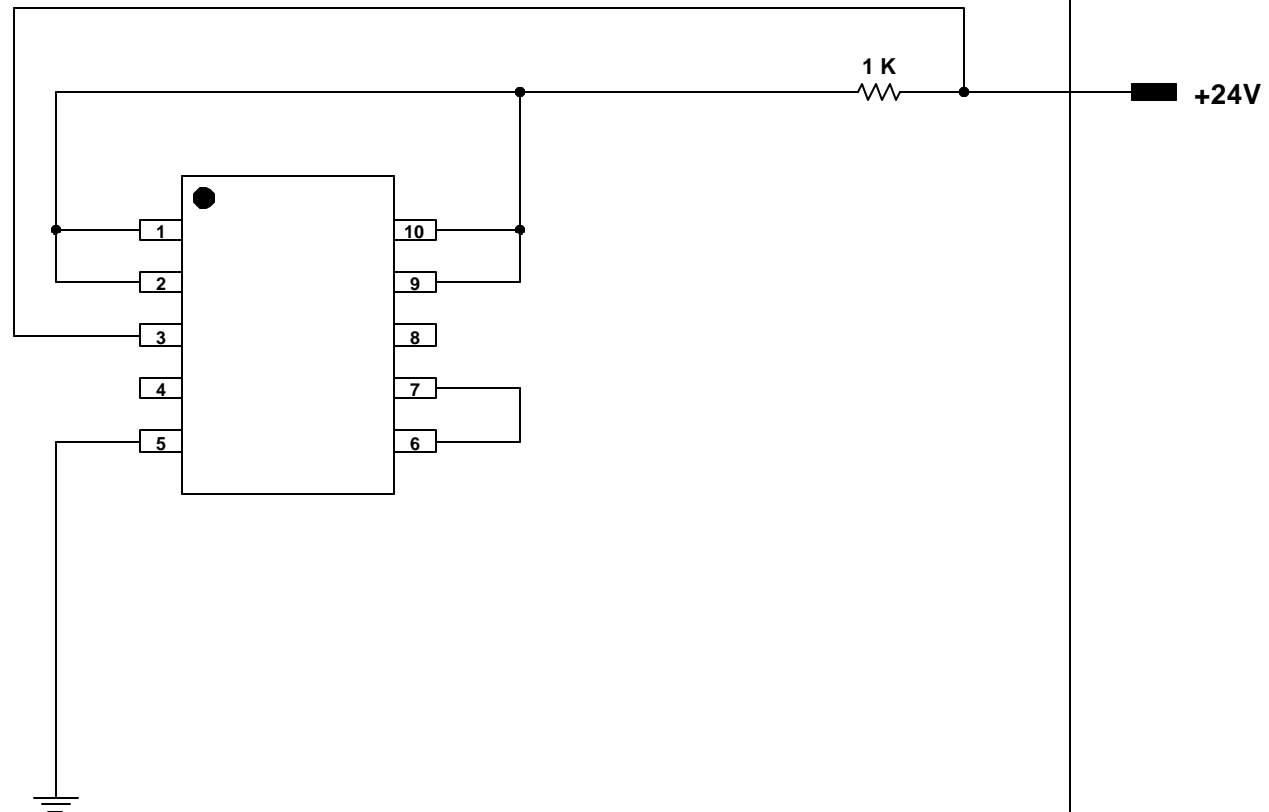




PKG. CODE: U10-2		SIGNATURES	DATE	 CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 68x94	PKG. DESIGN			BOND DIAGRAM #: 05-2501-0205	REV: A

ONCE PER SOCKET

ONCE PER BOARD



DEVICES: MAX 4069EUB (OX97Z)
PACKAGE: 10-uMAX
MAX. EXPECTED CURRENT = 0.25 mA

DRAWN BY: TEK TAN
NOTES: